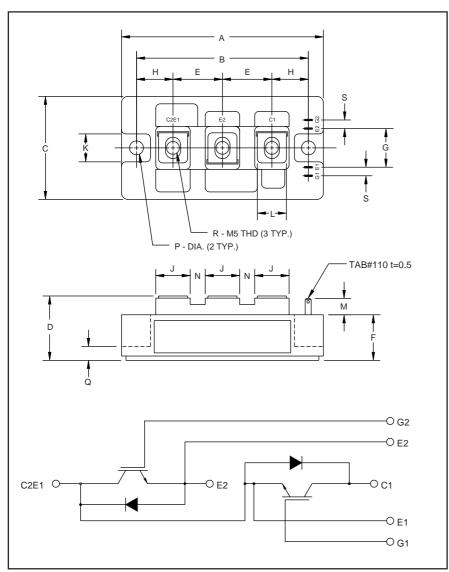
MITSUBISHI IGBT MODULES

CM100DY-24H

HIGH POWER SWITCHING USE INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
Α	3.70	94.0
В	3.150±0.01	80.0±0.25
С	1.89	48.0
D	1.18 Max.	30.0 Max.
Е	0.90	23.0
F	0.83	21.2
G	0.71	18.0
Н	0.67	17.0
J	0.62	16.0

Dimensions	Inches	Millimeters	
K	0.51	13.0	
L	0.47	12.0	
М	0.30	7.5	
N	0.28	7.0	
Р	0.256 Dia.	Dia. 6.5	
Q	0.31	8.0	
R	M5 Metric	M5	
S	0.16	4.0	



Description:

Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of two IGBTs in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- □ Low Drive Power
- ☐ Low V_{CE(sat)}
- ☐ Discrete Super-Fast Recovery Free-Wheel Diode
- ☐ High Frequency Operation
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:

- ☐ AC Motor Control
- ☐ Motion/Servo Control
- □ UPS
- □ Welding Power Supplies

Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM100DY-24H is a 1200V (V_{CES}), 100 Ampere Dual IGBT Module.

Туре	Current Rating Amperes	V _{CES} Volts (x 50)
CM	100	24



CM100DY-24H

HIGH POWER SWITCHING USE INSULATED TYPE

Absolute Maximum Ratings, T_i = 25 °C unless otherwise specified

	Symbol	Ratings	Units
Junction Temperature	Тј	-40 to 150	°C
Storage Temperature	T _{stg}	-40 to 125	°C
Collector-Emitter Voltage (G-E SHORT)	V _{CES}	1200	Volts
Gate-Emitter Voltage (C-E SHORT)	V _{GES}	±20	Volts
Collector Current (T _C = 25°C)	lc	100	Amperes
Peak Collector Current	I _{CM}	200*	Amperes
Emitter Current** (T _C = 25°C)	ΙΕ	100	Amperes
Peak Emitter Current**	I _{EM}	200*	Amperes
Maximum Collector Dissipation ($T_C = 25^{\circ}C, T_j \le 150^{\circ}C$)	P _c	780	Watts
Mounting Torque, M5 Main Terminal	-	1.47 ~ 1.96	N · m
Mounting Torque, M6 Mounting	-	1.96 ~ 2.94	N · m
Weight	-	270	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V _{iso}	2500	Vrms

^{*}Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating. **Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics, T_i = 25 $^{\circ}$ C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Collector-Cutoff Current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	1.0	mA
Gate Leakage Current	I _{GES}	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	0.5	μΑ
Gate-Emitter Threshold Voltage	V _{GE(th)}	I _C = 10mA, V _{CE} = 10V	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C = 100A, V _{GE} = 15V	-	2.5	3.4**	Volts
		I _C = 100A, V _{GE} = 15V, T _j = 150°C	_	2.25	_	Volts
Total Gate Charge	Q _G	V _{CC} = 600V, I _C = 100A, V _{GE} = 15V	_	500	_	nC
Emitter-Collector Voltage	V _{EC}	I _E = 100A, V _{GE} = 0V	_	_	3.5	Volts

^{**} Pulse width and repetition rate should be such that device junction temperature rise is negligible.

Dynamic Electrical Characteristics, T_i = 25 °C unless otherwise specified

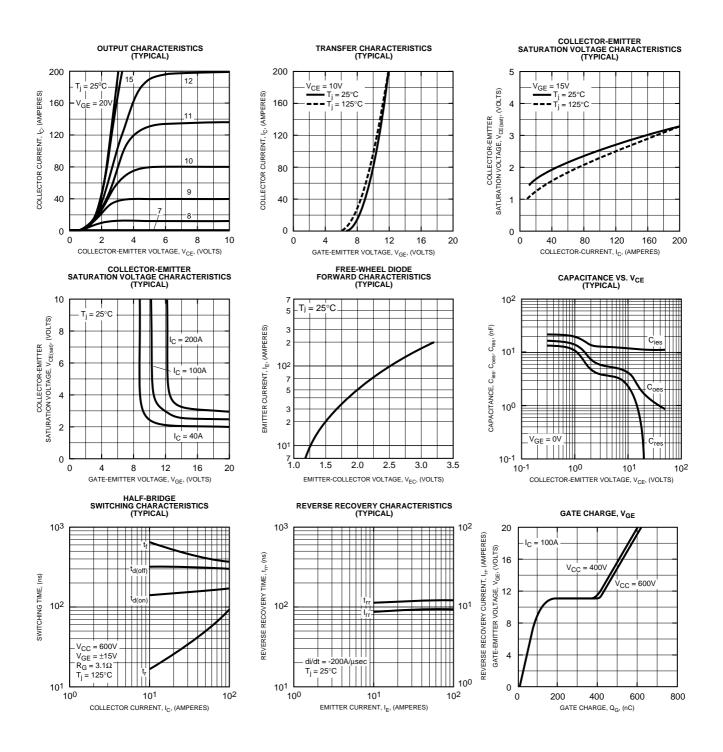
•		·]	•				
Characteristics		Symbol	Test Conditions	Min.	Тур.	Max.	Units
Input Capacitan	ice	C _{ies}		_	_	20	nF
Output Capacita	ance	C _{oes}	$V_{GE} = 0V$, $V_{CE} = 10V$	_	-	7	nF
Reverse Transfe	er Capacitance	C _{res}		_	_	4	nF
Resistive	Turn-on Delay Time	t _{d(on)}		_	_	250	ns
Load	Rise Time	t _r	$V_{CC} = 600V, I_{C} = 100A,$	_	-	350	ns
Switching	Turn-off Delay Time	t _{d(off)}	$V_{GE1} = V_{GE2} = 15V, R_G = 3.1\Omega$	_	_	300	ns
Time	Fall Time	t _f	_	_	_	350	ns
Diode Reverse	Recovery Time	t _{rr}	I _E = 100A, di _E /dt = -200A/μs	_	-	250	ns
Diode Reverse	Recovery Charge	Q _{rr}	$I_E = 100A$, $di_E/dt = -200A/\mu s$	_	0.74	_	μC

Thermal and Mechanical Characteristics, T_j = 25 $^{\circ}$ C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Thermal Resistance, Junction to Case	R _{th(j-c)}	Per IGBT	_	_	0.16	°C/W
Thermal Resistance, Junction to Case	R _{th(j-c)}	Per FWDi	_	-	0.35	°C/W
Contact Thermal Resistance	R _{th(c-f)}	Per Module, Thermal Grease Applied	-	_	0.065	°C/W

CM100DY-24H

HIGH POWER SWITCHING USE INSULATED TYPE



CM100DY-24H

HIGH POWER SWITCHING USE INSULATED TYPE

